

HiPerFRED

DPG10IM300UC

V_{RRM}	=	300 V
I _{fav}	=	10 A
t _{rr}	=	35 ns

High Performance Fast Recovery Diode Low Loss and Soft Recovery Single Diode

Part number

DPG10IM300UC

Marking on Product: PAOGUI



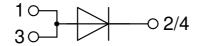
Backside: cathode

Package: TO-252 (DPak)

• Industry standard outline

• Epoxy meets UL 94V-0

RoHS compliant



Features / Advantages:

- Planar passivated chips
- Very low leakage current
- Very short recovery time
- Improved thermal behaviour
- Very low Irm-values
- Very soft recovery behaviour
 Avalanche voltage rated for reliable opera
- Avalanche voltage rated for reliable operation
 Soft reverse recovery for low EMI/RFI
- Low Irm reduces:
 - Power dissipation within the diode
- Turn-on loss in the commutating switch

Applications:

- Antiparallel diode for high frequency switching devices
- Anticonturation dias
- Antisaturation diode
- Snubber diode
- Free wheeling diode
 Rectifiers in switch mode power supplies (SMPS)
- Uninterruptible power supplies (UPS)

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IXYS reserves the right to change limits, conditions and dimensions.



DPG10IM300UC

Fast Diode					Ratings		
Symbol	Definition	Conditions		min.	typ.	max.	Unit
V _{RSM}	max. non-repetitive reverse blocki	ing voltage	$T_{v_J} = 25^{\circ}C$			300	V
V _{RRM}	max. repetitive reverse blocking v	oltage	$T_{VJ} = 25^{\circ}C$			300	V
I _R	reverse current, drain current	$V_{R} = 300 V$	$T_{vJ} = 25^{\circ}C$			1	μA
		$V_{R} = 300 V$	$T_{vJ} = 150^{\circ}C$			0.06	mA
VF	forward voltage drop	I _F = 10 A	$T_{vJ} = 25^{\circ}C$			1.27	V
		I _F = 20 A				1.45	V
		$I_{F} = 10 \text{ A}$	T _{vJ} = 150°C			0.98	V
		$I_{F} = 20 \text{ A}$				1.17	V
IFAV	average forward current	T _c = 150°C	$T_{vJ} = 175 \circ C$			10	Α
		rectangular d = 0.5					
V _{F0}	threshold voltage		$T_{vJ} = 175^{\circ}C$			0.74	V
r _F	slope resistance } for power in	oss calculation only				17.7	mΩ
R _{thJC}	thermal resistance junction to case	e				2.3	K/W
R _{thCH}	thermal resistance case to heatsir	nk			0.5		K/W
P _{tot}	total power dissipation		$T_c = 25^{\circ}C$			65	W
IFSM	max. forward surge current	$t = 10 \text{ ms}; (50 \text{ Hz}), \text{ sine}; V_{R} = 0 \text{ V}$	$T_{VJ} = 45^{\circ}C$			140	Α
C	junction capacitance	$V_{R} = 150 V f = 1 MHz$	$T_{VJ} = 25^{\circ}C$		15		pF
IRM	max. reverse recovery current		$T_{vJ} = 25 °C$		3		Α
		$I_{\rm F} = 10 \text{A}; V_{\rm R} = 200 \text{V}$	T _{vJ} = 125 °C		5.5		Α
t _{rr}	reverse recovery time	-di _F /dt = 200 A/μs	$T_{VJ} = 25 \degree C$		35		ns
)	T _{vJ} = 125 °C		45		ns

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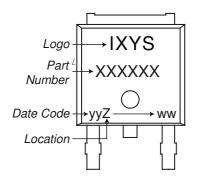


DPG10IM300UC

Package TO-252 (DPak)			Ratings			
Definition	Conditions	min.	typ.	max.	Unit	
RMS current	per terminal 1)			20	Α	
virtual junction temperature		-55		175	°C	
operation temperature		-55		150	°C	
storage temperature		-55		150	°C	
			0.3		g	
mounting force with clip		20		60	N	
	Definition RMS current virtual junction temperature operation temperature storage temperature	DefinitionConditionsRMS currentper terminal "virtual junction temperatureoperation temperaturestorage temperature	Definition Conditions min. RMS current per terminal " -55 virtual junction temperature -55 operation temperature -55 storage temperature -55	Definition Conditions min. typ. RMS current per terminal " - virtual junction temperature -55 operation temperature -55 storage temperature -55 0.3	DefinitionConditionsmin.typ.max.RMS currentper terminal "20virtual junction temperature-55175operation temperature-55150storage temperature-551500.30.3100	

¹⁾ I_{NMS} is typically limited by the pin-to-chip resistance (1); or by the current capability of the chip (2). In case of (1) and a product with multiple pins for one chip-potential, the current capability can be increased by connecting the pins as one contact.

Product Marking



Part description

- D = Diode
- P = HiPerFRED G = extreme fast
- 10 = Current Rating [A]
- IM = Single Diode
- 300 = Reverse Voltage [V] UC = TO-252AA (DPak)

Ordering	Ordering Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	DPG10IM300UC-TRL	PAOGUI	Tape & Reel	2500	505682
Alternative	DPG10IM300UC-TUB	PAOGUI	Tube	70	524908

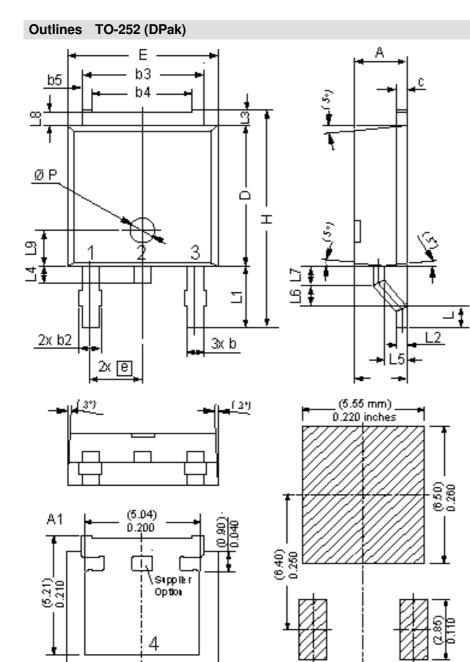
Similar Part	Package	Voltage class
DPG10I300PA	TO-220AC (2)	300

Equiva	alent Circuits for	Simulation	* on die level	$T_{VJ} = 175^{\circ}C$
) <u>R</u> ₀	Fast Diode		
V _{0 max}	threshold voltage	0.74		V
$\mathbf{R}_{0 \max}$	slope resistance *	14.5		mΩ

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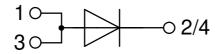
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Dim.	Millin	neters	Ind	nes
UIM.	min	max	min	max
A	2.20	2.40	0.087	0.094
A1	2.10	2.50	0.083	0.098
b	0.66	0.86	0.026	0.034
b2	-	0.96	-	0.038
b3	5.04	5.64	0.198	0.222
-b4	4.34	BSC	0.171	BSC
b5	0.50	BSC	0.020	BSC
С	0.40	0.86	0.016	0.034
D	5.90	6.30	0.232	0.248
E	6.40	6.80	0.252	0.268
е	2.10	2.50	0.083	0.098
Η	9.20	10.10	0.362	0.398
L	0.55	1.28	0.022	0.050
L1	2.50	2.90	0.098	0.114
L2	0.40	0.60	0.016	0.024
L3	0.50	0.90	0.020	0.035
L4	0.60	1.00	0.024	0.039
L5	0.82	1.22	0.032	0.048
L6	0.79	0.99	0.031	0.039
L7	0.81	1.01	0.032	0.040
L8	0.40	0.80	0.016	0.031
L9	1.50	BSC	0.059	BSC
ØΡ	1.00	BSC	0.039	BSC

Recommended min. foot print



(1.25) 0.050

(2.28) 0 0 90